2.0x1.25mm SMD CHIP LED LAMP

GREEN



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

PRELIMINARY SPEC

Features

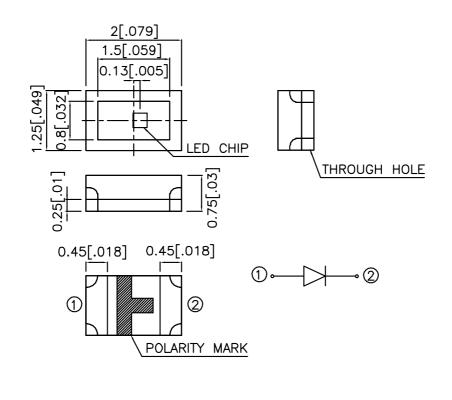
- •2.0mmx1.25mm SMT LED, 0.75mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACK LIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE : 2000PCS / REEL.

Description

APTK2012VGC

The Green source color devices are made with InGaN on SiC Light Emitting Diode. Static electricity and surge damage the LEDS. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes

All dimensions are in millimeters (inches).
Tolerance is ±0.1(0.004") unless otherwise noted.
Specifications are subject to change without notice.

REV NO: V.2 CHECKED: Allen Liu DATE: FEB/28/2005 DRAWN: W.J.ZHU

PAGE: 1 OF 4 ERP:1204000335

Selection Guide								
Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle			
			Min.	Тур.	201/2			
APTK2012VGC	GREEN (InGaN)	WATER CLEAR	700	200	100°			

Note: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at TA=25°C

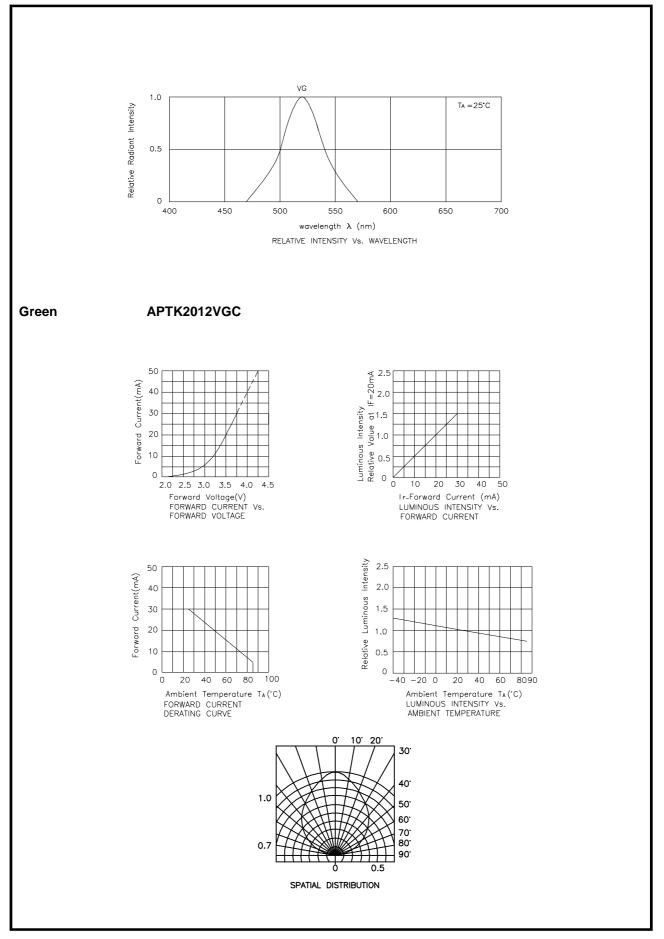
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	520		nm	IF=20mA
λD	Dominant Wavelength	Green	525		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	38		nm	IF=20mA
С	Capacitance	Green	45		pF	VF=0V;f=1MHz
Vf	Forward Voltage	Green	3.5	4.5	V	IF=20mA
IR	Reverse Current	Green		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation	105	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating / Storage Temperature	-40°C To +85°C		

Note:

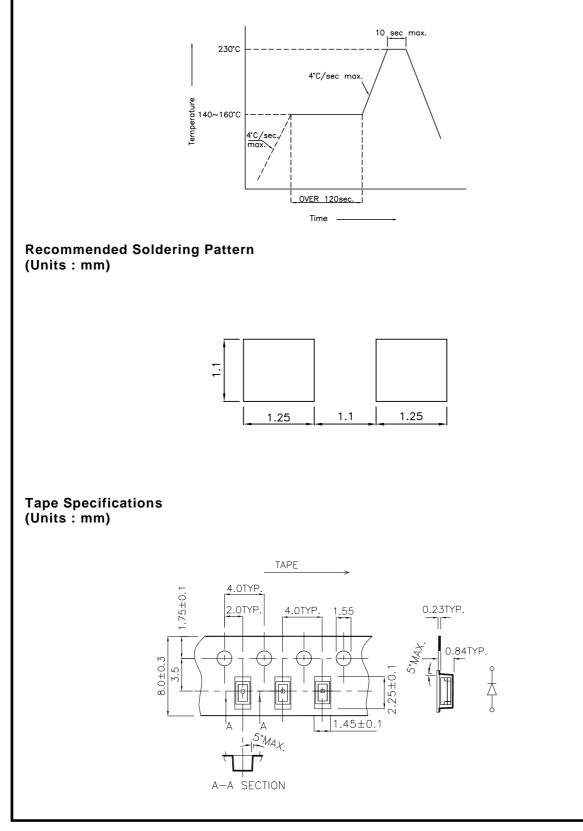
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



REV NO: V.2 CHECKED: Allen Liu DATE: FEB/28/2005 DRAWN: W.J.ZHU PAGE: 3 OF 4 ERP:1204000335

APTK2012VGC SMT Reflow Soldering Instructions

Number of reflow process shall be 2 times or less and cooling process to normal temperature is required between first and second soldering process.



REV NO: V.2 CHECKED: Allen Liu DATE: FEB/28/2005 DRAWN: W.J.ZHU PAGE: 4 OF 4 ERP:1204000335

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Kingbright: APTK2012VGC